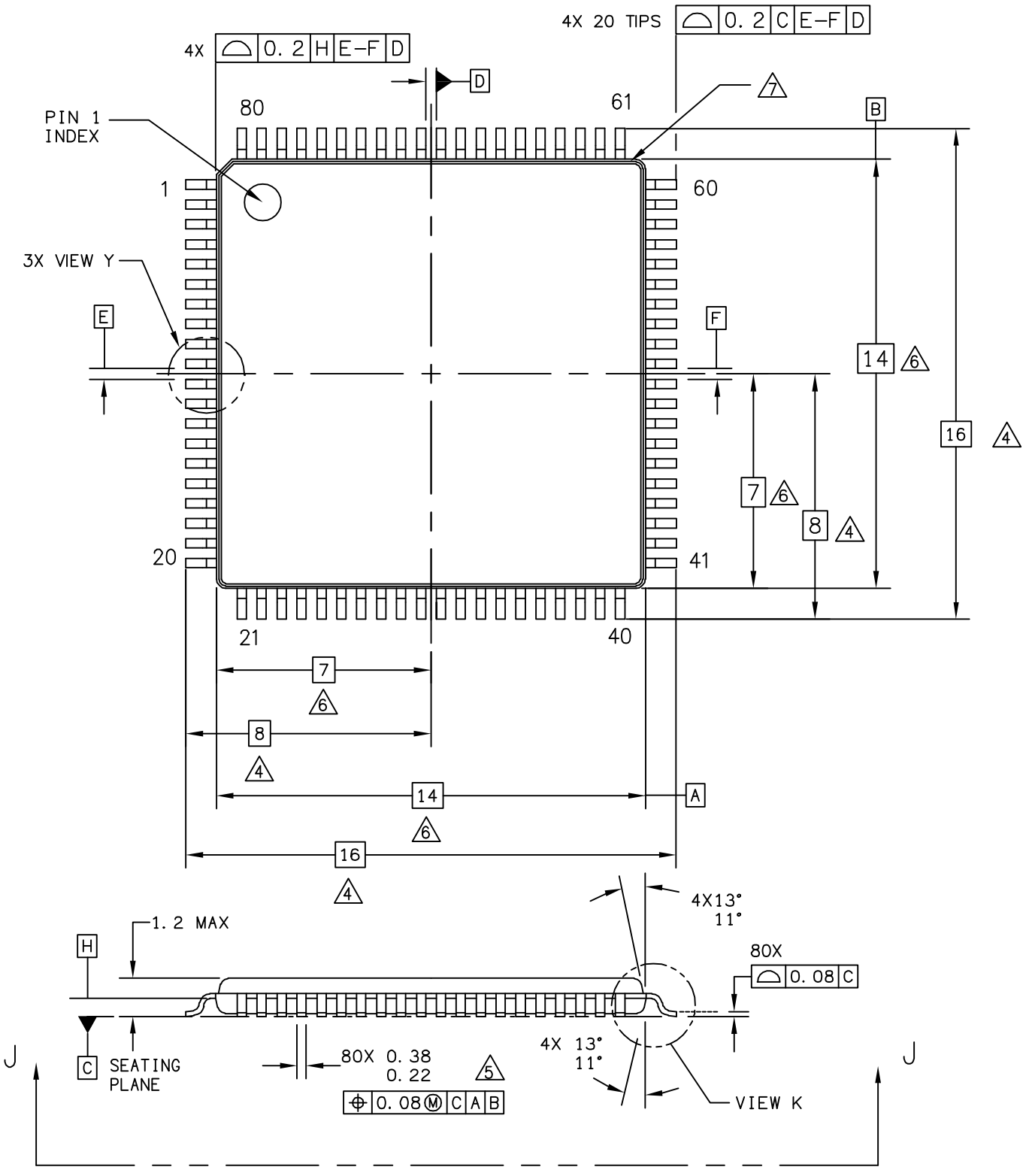
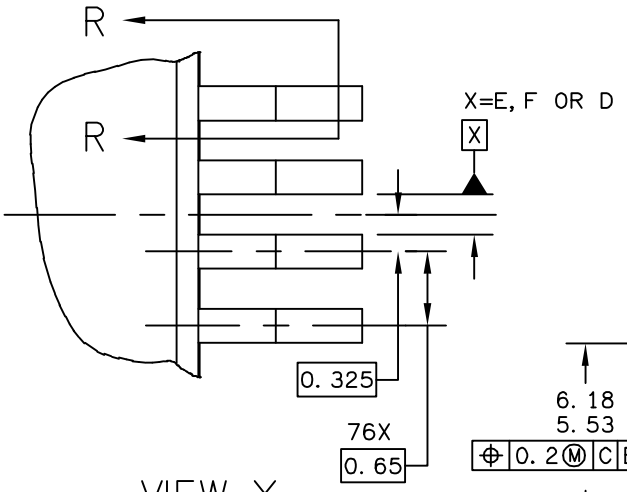


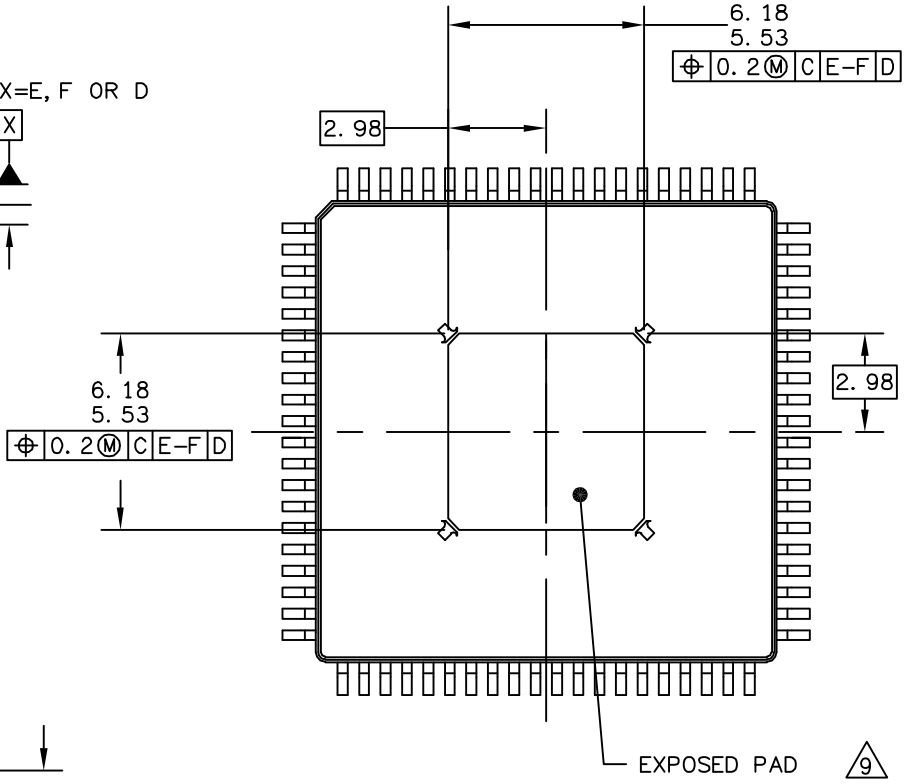
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:
QFP, 80 I/O, 14 X 14 PKG,
0.65 MM PITCH

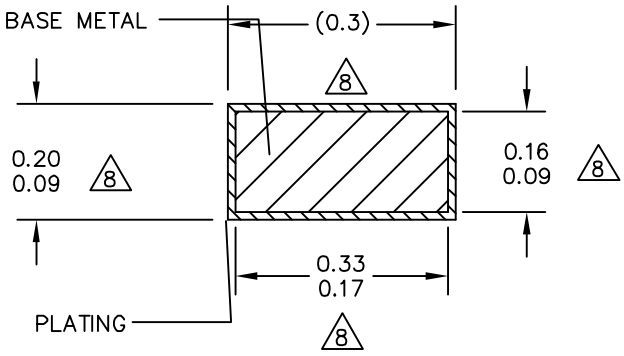
DOCUMENT NO: 98ARE10541D	REV: C
STANDARD: NON-JEDEC	
SOT513-2	17 DEC 2015



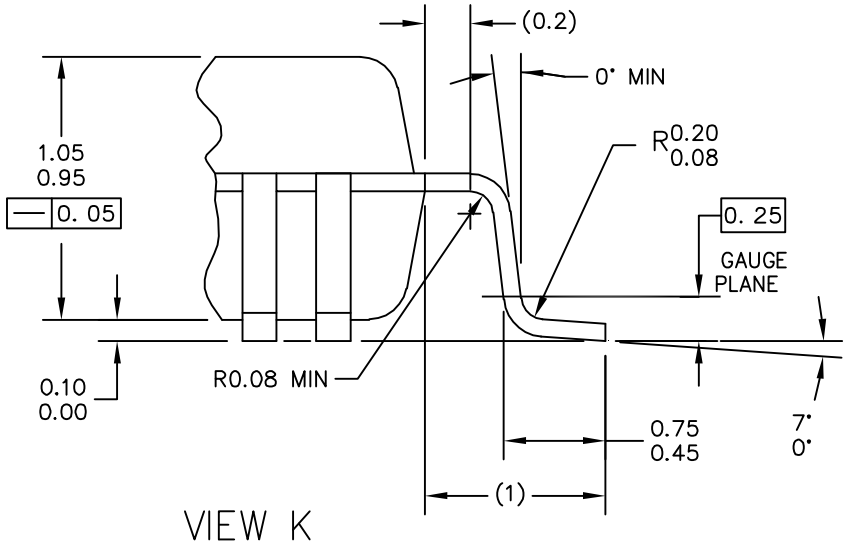
VIEW Y



VIEW J–J



SECTION R–R
ROTATED 90°CW



VIEW K

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TITLE: QFP, 80 I/O, 14 X 14 PKG, 0. 65 MM PITCH	DOCUMENT NO: 98ARE10541D	REV: C
	STANDARD: NON–JEDEC	
	SOT513–2	17 DEC 2015

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DATUMS E, F AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C
5. THIS DIMENSION DOES NOT INCLUDE DAMBER PROTRUSION. ALLOWABLE DAMBER PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 mm. DAMBER CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 mm.
6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.25 mm FROM THE LEAD TIP.
9. AT LEAST 80% OF THE EXPOSED PAD AREA SHOULD BE FREE OF RESIN.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ARE10541D	REV: C
QFP, 80 I/O, 14 X 14 PKG, 0.65 MM PITCH	STANDARD: NON-JEDEC	
	SOT513-2	17 DEC 2015